

General Description

FSMOS[®] MOSFET is based on Oriental Semiconductor's unique device design to achieve low $R_{DS(ON)}$, low gate charge, fast switching and excellent avalanche characteristics. The low V_{th} series is specially designed to use in synchronous rectification power systems with low driving voltage.

Features

- Low $R_{DS(ON)}$ & FOM
- Extremely low switching loss
- Excellent reliability and uniformity
- Fast switching and soft recovery



Applications

- PD charger
- Motor driver
- Switching voltage regulator
- DC-DC convertor
- Switching mode power supply

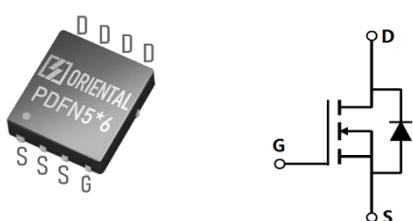
Key Performance Parameters

Parameter	Value	Unit
V_{DS}	60	V
I_D , pulse	480	A
$R_{DS(ON)}$ max @ $V_{GS}=10V$	3	mΩ
Q_g	66.1	nC

Marking Information

Product Name	Package	Marking
SFS06R03GF	PDFN5x6	SFS06R03G

Package & Pin information



Absolute Maximum Ratings at $T_j=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain source voltage	V_{DS}	60	V
Gate source voltage	V_{GS}	± 20	V
Continuous drain current ¹⁾ , $T_c=25^\circ\text{C}$	I_D	160	A
Pulsed drain current ²⁾ , $T_c=25^\circ\text{C}$	$I_{D,\text{pulse}}$	480	A
Continuous diode forward current ¹⁾ , $T_c=25^\circ\text{C}$	I_S	160	A
Diode pulsed current ²⁾ , $T_c=25^\circ\text{C}$	$I_{S,\text{Pulse}}$	480	A
Power dissipation ³⁾ , $T_c=25^\circ\text{C}$	P_D	168	W
Single pulsed avalanche energy ⁵⁾	E_{AS}	200	mJ
Operation and storage temperature	T_{stg}, T_j	-55 to 175	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal resistance, junction-case	$R_{\theta JC}$	0.89	$^\circ\text{C/W}$
Thermal resistance, junction-ambient ⁴⁾	$R_{\theta JA}$	62	$^\circ\text{C/W}$

Electrical Characteristics at $T_j=25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	BV_{DSS}	60			V	$V_{GS}=0 \text{ V}, I_D=250 \mu\text{A}$
Gate threshold voltage	$V_{GS(\text{th})}$	1.3		2.5	V	$V_{DS}=V_{GS}, I_D=250 \mu\text{A}$
Drain-source on-state resistance	$R_{DS(\text{ON})}$		2.3	3.0	$\text{m}\Omega$	$V_{GS}=10 \text{ V}, I_D=20 \text{ A}$
Drain-source on-state resistance	$R_{DS(\text{ON})}$		3.5	4.0	$\text{m}\Omega$	$V_{GS}=4.5 \text{ V}, I_D=10 \text{ A}$
Gate-source leakage current	I_{GSS}			100	nA	$V_{GS}=20 \text{ V}$
				-100		$V_{GS}=-20 \text{ V}$
Drain-source leakage current	I_{DSS}			1	μA	$V_{DS}=60 \text{ V}, V_{GS}=0 \text{ V}$

Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C _{iss}		5377		pF	V _{GS} =0 V, V _{DS} =25 V, f=100 kHz
Output capacitance	C _{oss}		1666		pF	
Reverse transfer capacitance	C _{rss}		77.7		pF	
Turn-on delay time	t _{d(on)}		22.5		ns	V _{GS} =10 V, V _{DS} =30 V, R _G =2 Ω, I _D =25 A
Rise time	t _r		6.7		ns	
Turn-off delay time	t _{d(off)}		80.3		ns	
Fall time	t _f		26.8		ns	

Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	Q _g		66.1		nC	V _{GS} =10 V, V _{DS} =30 V, I _D =25 A
Gate-source charge	Q _{gs}		10.7		nC	
Gate-drain charge	Q _{gd}		10.9		nC	
Gate plateau voltage	V _{plateau}		2.9		V	

Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward voltage	V _{SD}			1.3	V	I _s =20 A, V _{GS} =0 V
Reverse recovery time	t _{rr}		68.3		ns	
Reverse recovery charge	Q _{rr}		73.0		nC	
Peak reverse recovery current	I _{rrm}		1.9		A	

Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of R_{θJA} is measured with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with T_a=25 °C.
- 5) V_{DD}=30 V, V_{GS}=10 V, L=0.3 mH, starting T_j=25 °C.

Electrical Characteristics Diagrams

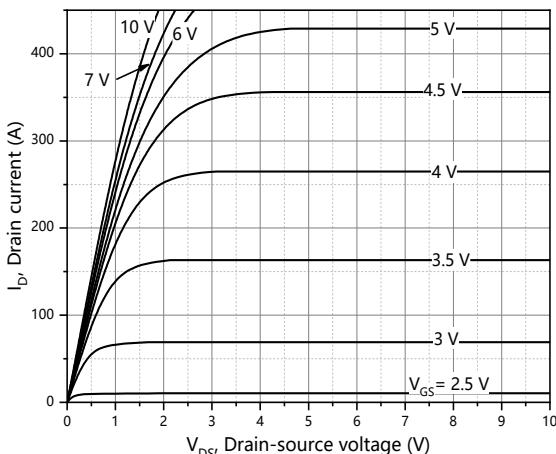


Figure 1. Typ. output characteristics

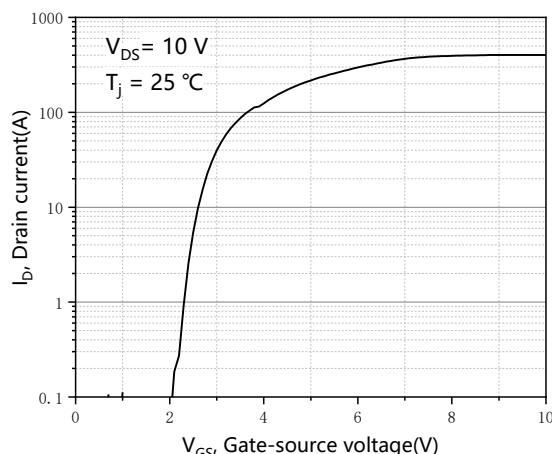


Figure 2. Typ. transfer characteristics

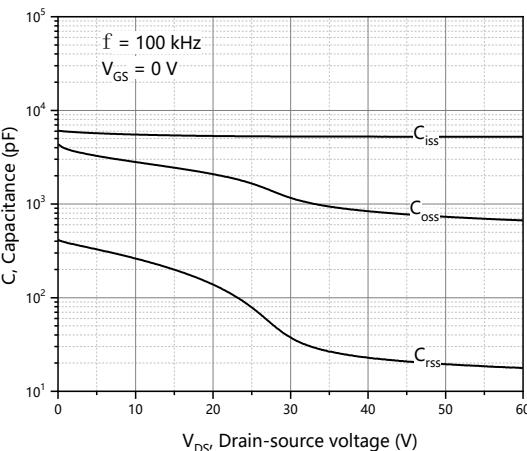


Figure 3. Typ. capacitances

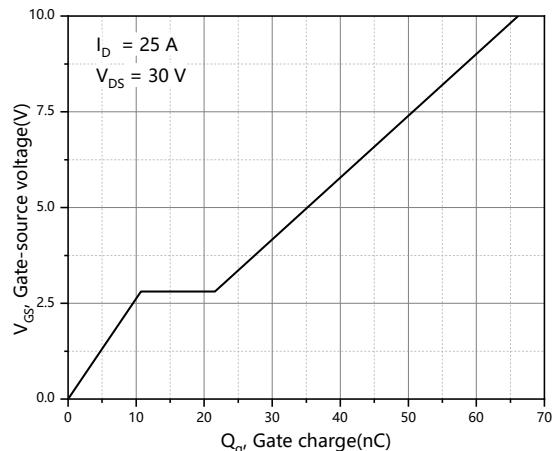


Figure 4. Typ. gate charge

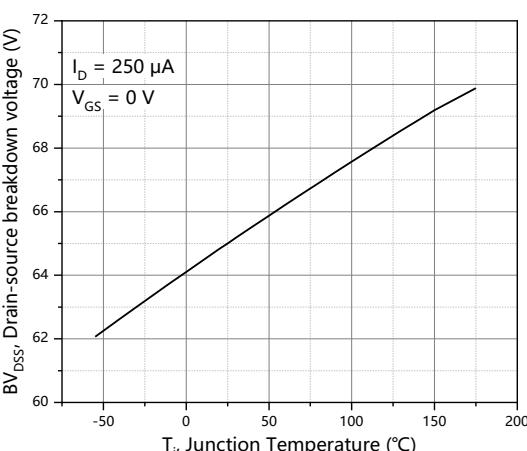


Figure 5. Drain-source breakdown voltage

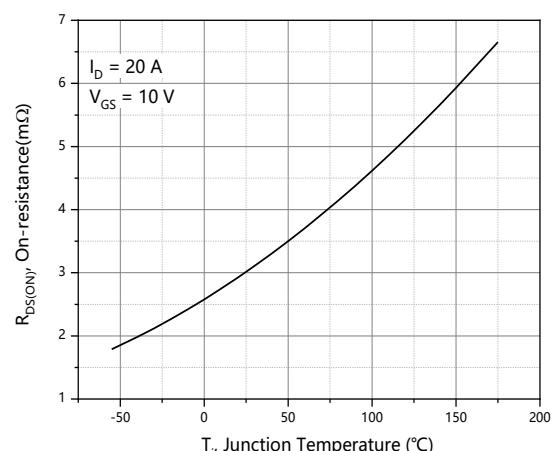
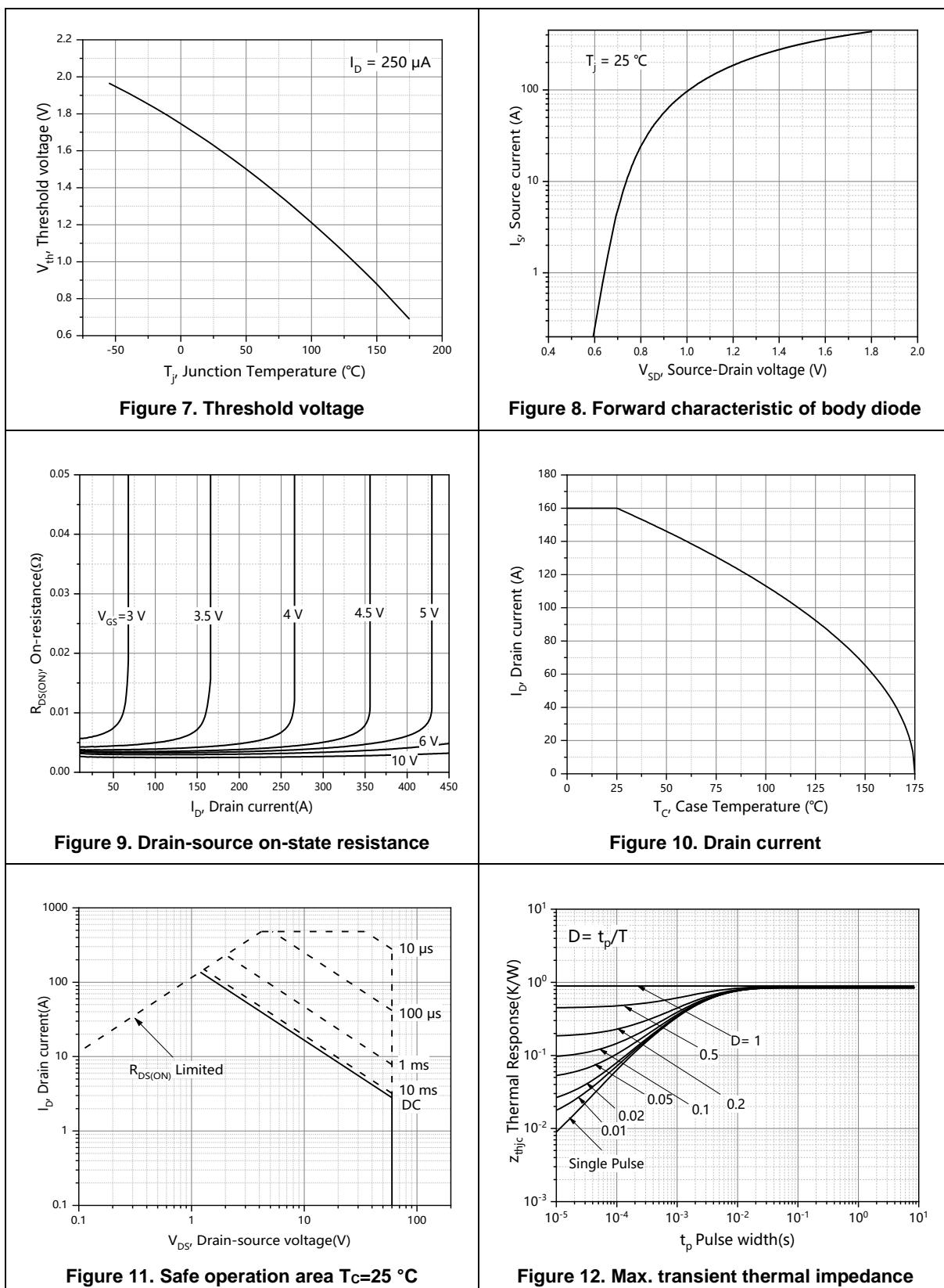


Figure 6. Drain-source on-state resistance



Test circuits and waveforms

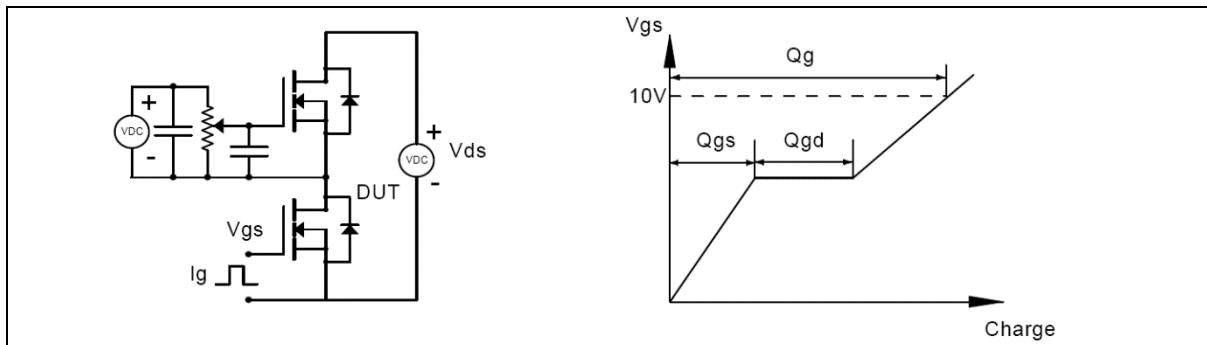


Figure 1. Gate charge test circuit & waveform



Figure 2. Switching time test circuit & waveforms



Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms

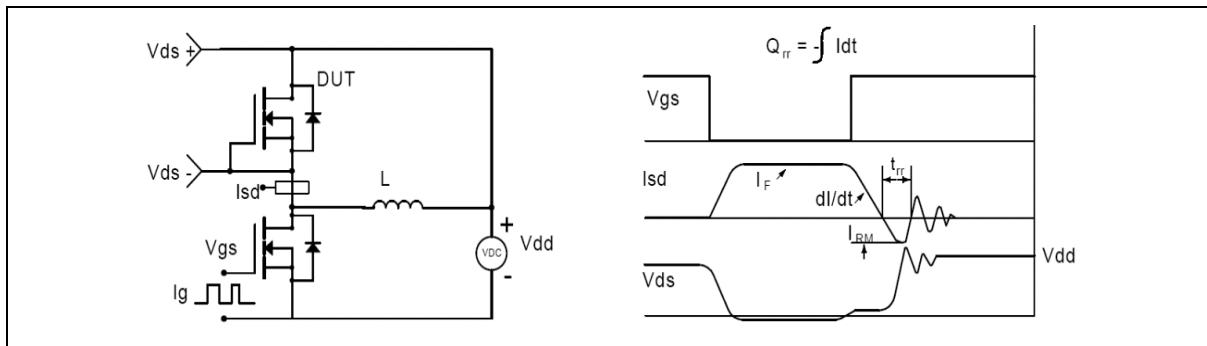
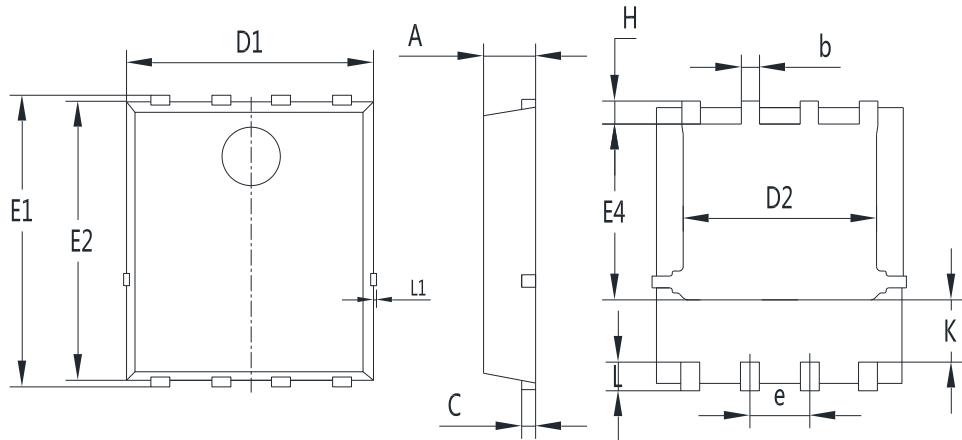


Figure 4. Diode reverse recovery test circuit & waveforms

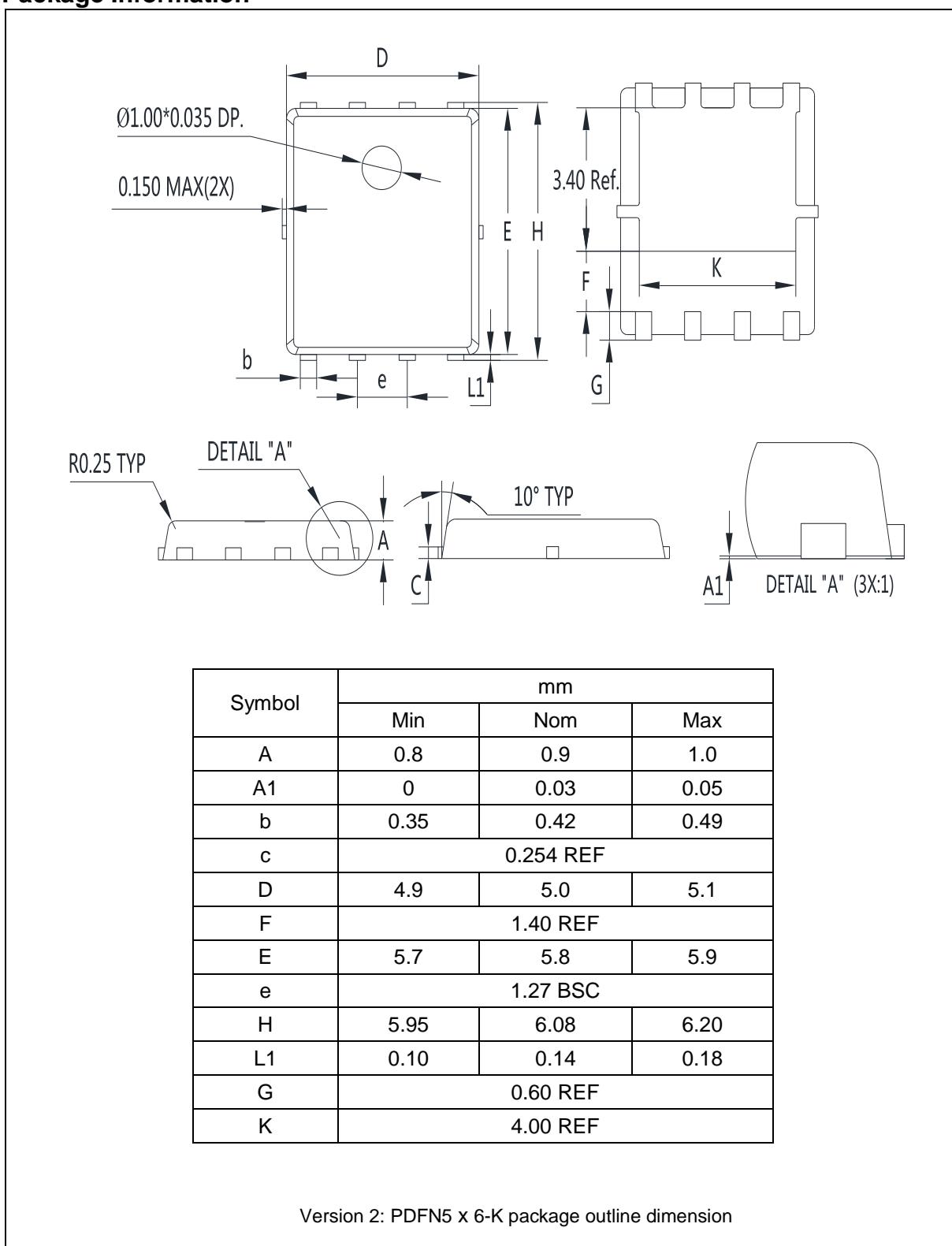
Package Information



Symbol	mm		
	Min	Nom	Max
A	1.00	1.10	1.20
b	0.30	0.40	0.50
c	0.154	0.254	0.354
D1	5.00	5.20	5.40
D2	3.80	4.10	4.25
e	1.17	1.27	1.37
E1	5.95	6.15	6.35
E2	5.66	5.86	6.06
E4	3.52	3.72	3.92
H	0.40	0.50	0.60
L	0.30	0.60	0.70
L1	0.12 REF		
K	1.15	1.30	1.45

Version 1: PDFN5 x 6-P package outline dimension

Package Information



Ordering Information

Package Type	Units/Reel	Reels / Inner Box	Units/Inner Box	Inner Boxes/Carton Box	Units/Carton Box
PDFN5 x 6-P	5000	2	10000	5	50000
PDFN5 x 6-K	5000	2	10000	5	50000

Product Information

Product	Package	Pb Free	RoHS	Halogen Free
SFS06R03GF	PDFN5 x 6	yes	yes	yes

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